M5M5256BP,BFP,BKP-70,-85,-10,-12,-15,-70L, -85L,-10L,-12L,-15L,-70LL,-85LL,-10LL,-12LL,-15LL

262144-BIT (32768-WORD BY 8-BIT) CMOS STATIC RAM

DESCRIPTION

This M5M5256BP, BFP, BKP is a 262,144-bit CMOS static RAM organized as 32,768-words by 8-bits which is fabricated using high-performance double polysilicon CMOS technology. The use of resistive load NMOS cells and CMOS periphery result in a high-density and low-power static RAM. It is ideal for the memory systems which require simple interface.

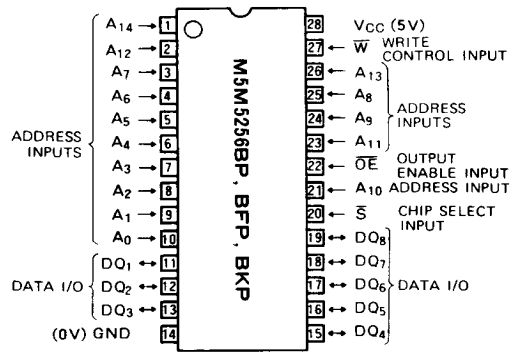
The stand-by current is low enough for a battery back-up application. It is mounted in a standard 28 pin package and configured in an industrial standard 32K x 8-bit pinout.

FEATURES

Type	Access time (max)	Power supply current	
		Active (max)	Stand-by (max)
M5M5256BP, BFP, BKP-70	70ns	70mA	2mA
M5M5256BP, BFP, BKP-85	85ns		
M5M5256BP, BFP, BKP-10	100ns		
M5M5256BP, BFP, BKP-12	120ns		
M5M5256BP, BFP, BKP-15	150ns		
M5M5256BP, BFP, BKP-70L	70ns		100 μA (V_{CC}=5.5V) 50 μA (V_{CC}=3.0V)
M5M5256BP, BFP, BKP-85L	85ns		
M5M5256BP, BFP, BKP-10L	100ns		
M5M5256BP, RFP, BKP-12L	120ns		
M5M5256BP, BFP, BKP-15L	150ns		
M5M5256BP, BFP, BKP-70LL	70ns		20 μA (V_{CC}=5.5V) 10 μA (V_{CC}=3.0V)
M5M5256BP, BFP, BKP-85LL	85ns		
M5M5256BP, BFP, BKP-10LL	100ns		
M5M5256BP, BFP, BKP-12LL	120ns		
M5M5256BP, BFP, BKP-15LL	150ns		

- Single +5V Power Supply
- No Clocks, No Refresh
- Data-Hold on +2V Power Supply
- Directly TTL Compatible: All Inputs and Outputs
- Three-State Outputs: OR-tie Capability

PIN CONFIGURATION (TOP VIEW)



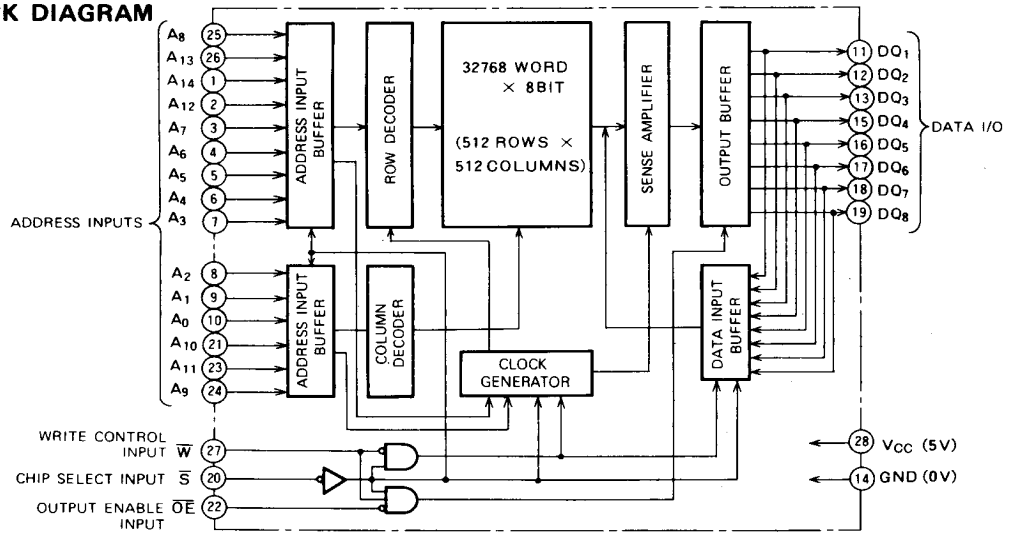
Outline 28P4 (BP)
28P2W-C (BFP)
28P4Y (BKP)

- Simple Memory Expantion by $\overline{S}$
- $\overline{OE}$ Prevents Data Contention in the I/O Bus
- Common Data I/O
- Package
  - M5M5256BP . . . . . 28 Pin 600 mil DIP
  - M5M5256BKP . . . . . 28 Pin 300 mil DIP
  - M5M5256BFP . 28 Pin Small Outline Package (SOP)

APPLICATION

Small Capacity Memory Units.

BLOCK DIAGRAM



MITSUBISHI ELECTRIC

M5M5256BP,BFP,BKP-70,-85,-10,-12,-15,-70L,-85L, -10L,-12L,-15L,-70LL,-85LL,-10LL,-12LL,-15LL

262144-BIT (32768-WORD BY 8-BIT) CMOS STATIC RAM

FUNCTION

The operation mode of the M5M5256BP, BFP, BKP is determined by a combination of the device control inputs $\overline{S}$, $\overline{W}$ and $\overline{OE}$. Each mode is summariezed in the function table.

A write cycle is executed whenever the low level $\overline{W}$ overlaps with the low level $\overline{S}$. The address must be set up before the write cycle and must be stable during the entire cycle. The data is latched into a cell on the trailing edge of $\overline{W}$, $\overline{S}$, whichever occurs first, requiring the set-up and hold time relative to these edge to be maintained. The output enable $\overline{OE}$ directly controls the output stage. Setting the $\overline{OE}$ at a high level, the output stage is in a high-impedance state, and the data bus contention problem in the write cycle is eliminated.

A read cycle is executed by setting $\overline{W}$ at a high level and $\overline{OE}$ at a low level while $\overline{S}$ are in an active state.

When setting $\overline{S}$ at a high level, the chip is in a non-selectable mode in which both reading and writing are disabled. In this mode, the output stage is in a high-impedance state, allowing OR-tie with other chips and memory expantion by $\overline{S}$. The power supply current is reduced as low as the stand-by current which is specified as I_{CC3} or I_{CC4}, and the memory data can be held +2V power supply, enabling battery back-up operation during power failure or power-down operation in the non-selected mode.

FUNCTION TABLE

$\overline{S}$	$\overline{W}$	$\overline{OE}$	Mode	DQ	I_{CC}
H	X	X	Non selection	High-impedance	Standby
L	L	X	Write	D_{IN}	Active
L	H	L	Read	D_{OUT}	Active
L	H	H		High-impedance	Active

ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Conditions	Ratings	Unit
V_{CC}	Supply voltage	With respect to GND	−0.3～7	V
V_I	Input voltage		−0.3～V_{CC}+0.3	V
V_O	Output voltage		0～V_{CC}	V
Pd	Power dissipation	Ta = 25°C	700	mW
Topr	Operating temperature		0～70	°C
Tstg	Storage temperature		−65～150	°C

ELECTRICAL CHARACTERISTICS (T_a = 0～70°C, V_{CC} ±5V ±10%, unless otherwise noted)

Symbol	Parameter	Test conditions		Limits			Unit
				Min	Typ	Max	
V_{IH}	High input voltage			2.2		V_{CC}+0.3	V
V_{IL}	Low input voltage			−0.3		0.8	V
V_{OH}	High output voltage	I_{OH} = −1mA		2.4			V
V_{OL}	Low output voltage	I_{OL} = 2mA				0.4	V
I_I	Input leakage current	V_I = 0～V_{CC}				±1	μA
I_O	Output leakage current	$\overline{S}$ = V_{IH} or $\overline{OE}$ = V_{IH}, $V_{I/O}$ = 0～V_{CC}				±1	μA
I_{CC1}	Active supply current (AC, MOS level)	$\overline{S}$ < 0.2, $\overline{W}$ > V_{CC} − 0.2, Output open Other input < 0.2 or > V_{CC} − 0.3 Min. cycle			30	65	mA
I_{CC2}	Active supply current (AC, TTL level)	$\overline{S}$ = V_{IL}, $\overline{W}$ = V_{IH}, Output open Other input = V_{IL} or V_{IH} Min. cycle			35	70	mA
I_{CC3}	Stand by supply current	$\overline{S}$ ≧ V_{CC} − 0.2V Other inputs = 0～V_{CC}	BP, BFP, BKP			2	mA
			BP, BFP, BKP-L			100	μA
			BP, BFP, BKP-LL			20	μA
I_{CC4}	Stand by supply current	$\overline{S}$ = V_{IH}, Other inputs = 0～V_{CC}				3	mA
C_i	Input capacitance (T_a = 25°C)	V_I = GND, V_I = 25mVrms, f = 1MHz				6	pF
C_O	Output capacitance (T_a = 25°C)	V_O = GND, V_O = 25mVrms, f = 1MHz				8	pF

Note 1 Direction for current flowing into IC is indicated as positive (no mark)
2 Typical value is V_{CC} = 5V, T_a = 25°C

SWITCHING CHARACTERISTICS (T_a = 0 ~ 70°C, V_{CC} = 5V ± 10%, unless otherwise noted)

Read cycle

Symbol	Parameter	Limits										Unit
		M5M5256-70 M5M5256-70L M5M5256-70LL		M5M5256-85 M5M5256-85L M5M5256-85LL		M5M5256-10 M5M5256-10L M5M5256-10LL		M5M5256-12 M5M5256-12L M5M5256-12LL		M5M5256-15 M5M5256-15L M5M5256-15LL		
		Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
t_{CR}	Read cycle time	70		85		100		120		150		ns
$t_{a(A)}$	Address access time		70		85		100		120		150	ns
$t_{a(S)}$	Chip select access time		70		85		100		120		150	ns
$t_{a(OE)}$	Output enable access time		35		45		50		60		75	ns
$t_{dis(S)}$	Output disable time after $\overline{S}$ high		30		30		35		40		45	ns
$t_{dis(OE)}$	Output disable time after $\overline{OE}$ high		25		30		35		40		45	ns
$t_{en(S)}$	Output enable time after $\overline{S}$ low	5		5		10		10		10		ns
$t_{en(OE)}$	Output enable time after $\overline{OE}$ low	5		5		10		10		10		ns
$t_{v(A)}$	Data valid time after address change	20		20		20		20		20		ns

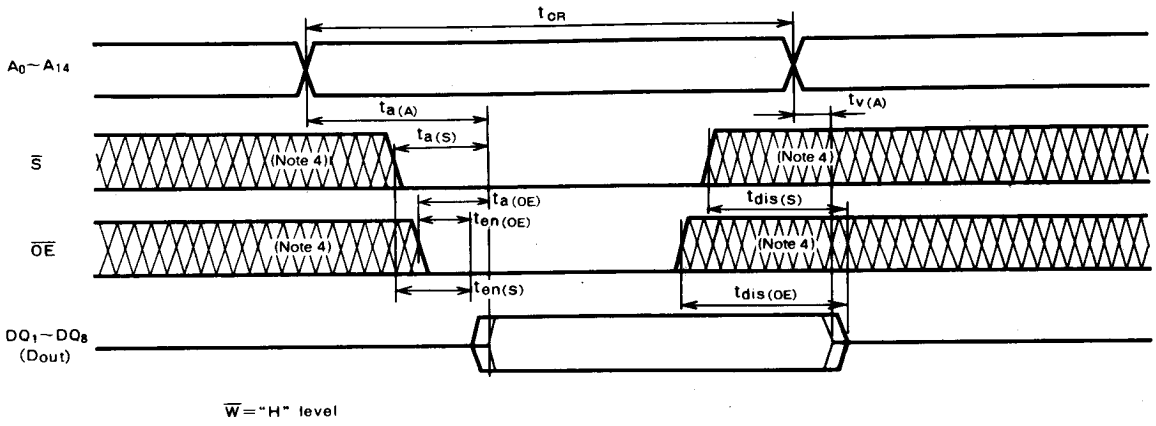
TIMING REQUIREMENTS (T_a = 0 ~ 70°C, V_{CC} = 5V ± 10%, unless otherwise noted)

Write cycle

Symbol	Parameter	Limits										Unit
		M5M5256-70 M5M5256-70L M5M5256-70LL		M5M5256-85 M5M5256-85L M5M5256-85LL		M5M5256-10 M5M5256-10L M5M5256-10LL		M5M5256-12 M5M5256-12L M5M5256-12LL		M5M5256-15 M5M5256-15L M5M5256-15LL		
		Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
t_{CW}	Write cycle time	70		85		100		120		150		ns
$t_{w(W)}$	Write pulse width	55		60		60		70		80		ns
$t_{su(A)}$	Address set up time	0		0		0		0		0		ns
$t_{su(A-\overline{W}H)}$	Address set up time with respect to $\overline{W}$ high	65		75		80		85		90		ns
$t_{su(S)}$	Chip select set up time	65		75		80		85		90		ns
$t_{su(D)}$	Data set up time	30		35		35		40		50		ns
$t_{h(D)}$	Data hold time	0		0		0		0		0		ns
$t_{rec(W)}$	Write recovery time	0		0		0		0		0		ns
$t_{dis(W)}$	Output disable time after $\overline{W}$ low		25		30		35		40		45	ns
$t_{dis(OE)}$	Output disable time after $\overline{OE}$ high		25		30		35		40		45	ns
$t_{en(W)}$	Output enable time after $\overline{W}$ high	5		5		10		10		10		ns
$t_{en(OE)}$	Output enable time after $\overline{OE}$ low	5		5		10		10		10		ns

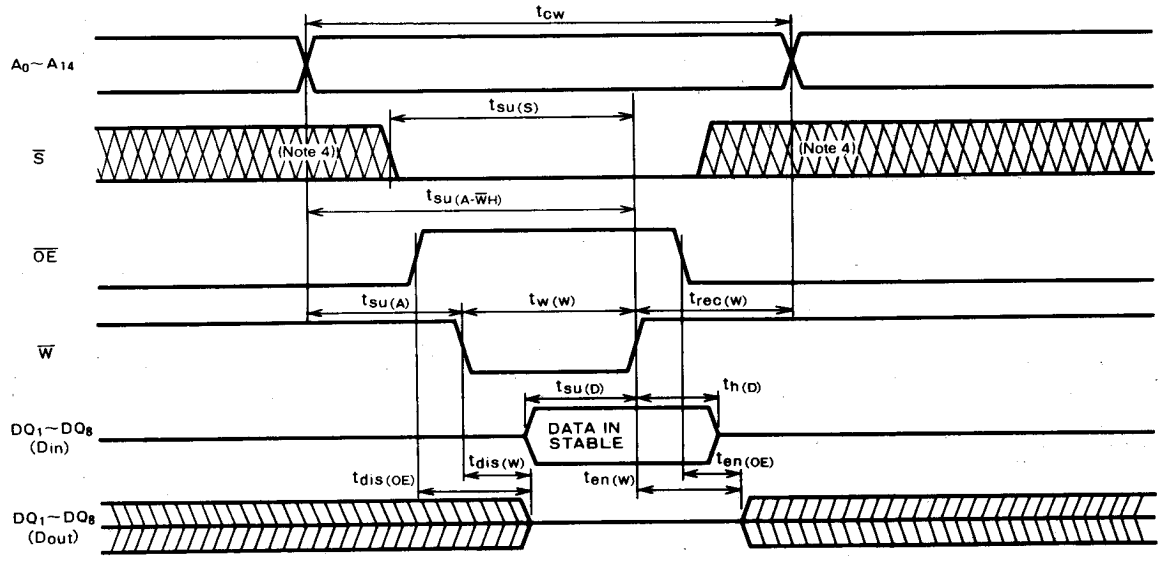
TIMING DIAGRAM

Read cycle

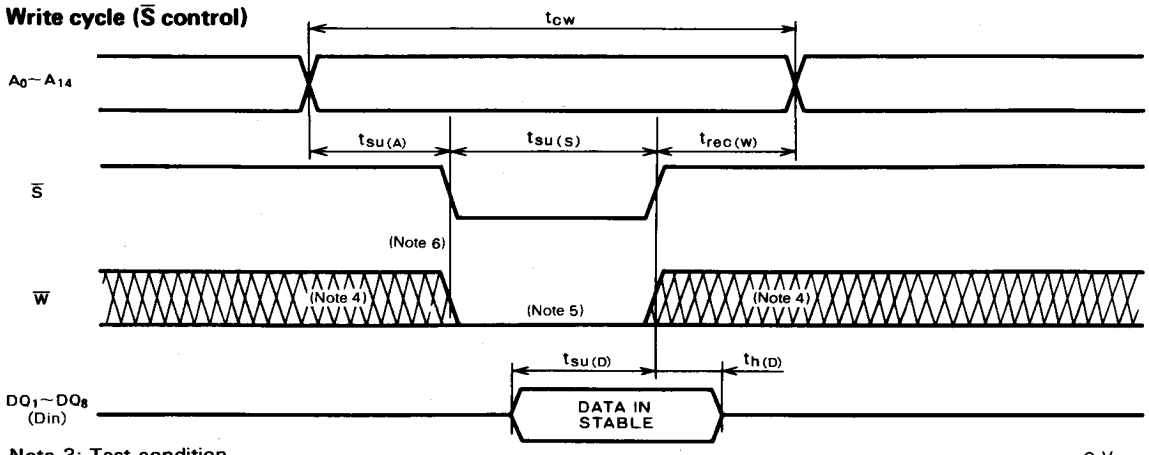


W="H" level

Write cycle (W control)



Write cycle ($\overline{S}$ control)



Note 3: Test condition

Input pulse level .... V_{IH} = 2.4V, V_{IL} = 0.6V

Input rise and fall time 10ns

Reference level ..... $V_{OH} = V_{OL}$ = 1.5V

Transition is measured ±500mV from steady state voltage. (for t_{en}, t_{dis})

Output loads ..... Fig. 1, C_L = 100pF (BP, BFP, BKP-85, -10, -12, -15, -85L, -10L, -12L, -15L, -85LL, -10LL, -12LL, -15LL)

C_L = 30pF (BP, BFP, BKP-70, -70L, -70LL)

C_L = 5pF (for t_{en}, t_{dis})

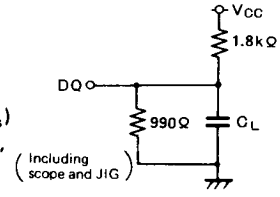


Fig. 1 Output load

Note 4: Hatching indicates the state is don't care.
5: Writing is executed in overlap of $\overline{S}$ and $\overline{W}$ low.
6: If $\overline{W}$ goes low simultaneously with or prior to $\overline{S}$, the output remains in the high-impedance state.
7: Don't apply inverted phase signal externally when DQ pin is in output mode.

POWER DOWN CHARACTERISTICS

ELECTRICAL CHARACTERISTICS (T_a = 0 ~ 70°C, unless otherwise noted)

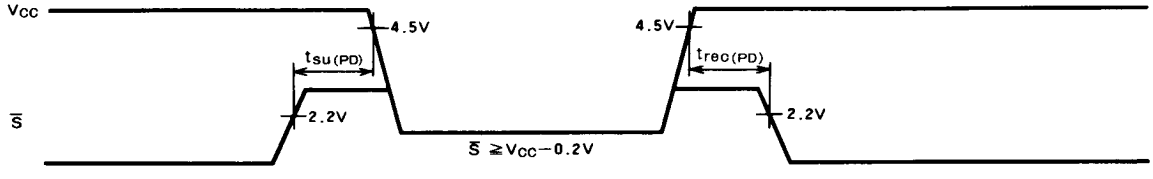
Symbol	Parameter	Test conditions		Limits			Unit
				Min	Typ	Max	
$V_{CC(PD)}$	Power down supply voltage			2			V
$V_{I(\overline{S})}$	Chip select input $\overline{S}$	2.2V ≦ $V_{CC(PD)}$		2.2			V
		2V ≦ $V_{CC(PD)}$ ≦ 2.2V			$V_{CC(PD)}$		
$I_{CC(PD)}$	Power down supply current	V_{CC} = 3V, Other inputs = 3V	BP, BFP, BKP			2	mA
			BP, BFP, BKP-L			50	μA
			BP, BFP, BKP-LL			10*	μA

* T_a = 25°C, $I_{CC(PD)}$ = 1μA

TIMING REQUIREMENTS (T_a = 0 ~ 70°C, unless otherwise noted)

Symbol	Parameter	Test conditions	Limits			Unit
			Min	Typ	Max	
$t_{su(PD)}$	Power down setup time		0			ns
$t_{rec(PD)}$	Power down recovery time		t_{CR}			ns

POWER DOWN CHARACTERISTICS



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